

PRODUCT SPECIFICATION

CDTECH Model: **S020BQ01HN**

CUSTOMER Model: **-**

Description: **2.0 " TFT-LCD Module**

Version: **2.0**

CDTECH	PREPARED BY	CHECKED BY	APPROVED BY
SIGNATURE			
DATE	2025.3.17	2025.3.17	2025.3.17

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1. General Specifications

1.1 LCM General Information

Item	Specification	Unit
LCD Size	2.0	inch
Number of Pixels	240 (H) RGB x 320 (V)	pixels
Display Mode	Normally Black	-
Viewing Direction	80/80/80/80 (Min) 85/85/85/85 (Typ.)	-
Interface	SPI	-
Display Colors	262K	colors
Outline Dimension	34.60 (H) x 47.80 (V) x 2.10 (D)	mm
Active Area	30.60 (H) x 40.80 (V)	mm
Pixel Pitch	0.1275 (H) x 0.1275 (V)	mm
Driver IC	ST7789P3	-
Operation Temperature	-20~70	°C
Storage Temperature	-30~80	°C

Note1:Requirements on environmental protection RoHS compliant.

2. Absolute Maximum Ratings

Item	Symbol	MIN.	MAX.	Unit	Note
Analog Supply voltage	VDD	-0.3	4.6	V	Note 1
Digital supply voltage	VDDI	-0.3	4.0	V	Note 1

Note 1:Permanent damage may occur to the LCD module if beyond this specification.

Functional operation should be restricted to the conditions described under normal operating conditions.

3. Electrical Characteristics

3.1 Recommended Operating Condition for TFT LCD

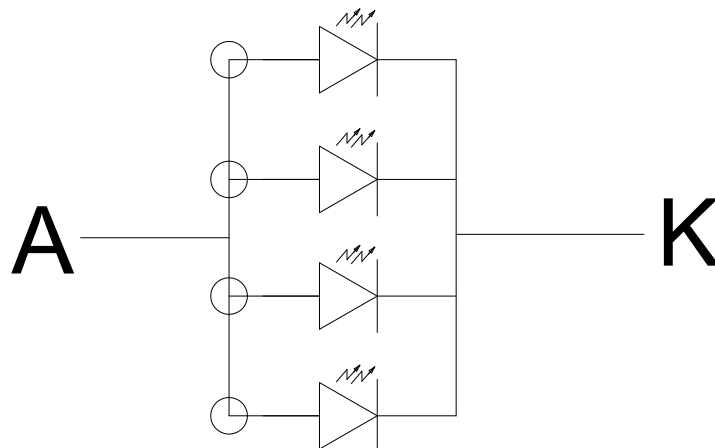
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Analog Supply voltage	VDD	2.4	2.8	3.3	V	
Analog supply current	I _{VDD}	2	5	8	mA	VDD=2.8V (white)
Logic supply voltage	VDDI	1.65	1.8	3.3	V	
Logic supply current	I _{VDDI}	1	3	5	mA	VDDI=1.8V
Logic input voltage	V _{IH}	0.7*VDDI	-	VDDI	V	
	V _{IL}	GND	-	0.3*VDDI	V	

3.2 Recommended Driving Condition for Backlight

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Driving Current	I _F	-	80	-	mA	
Driving Voltage	V _F	2.7	-	3.4	V	
Power consumption	W _{BL}	0.216	-	0.272	W	
LED Life-Time	N/A	-	50,000	-	Hours	Ta=25°C Note 1

Note 1: LED lifetime is defined as the module brightness decay 50% of original brightness at Ta=25 degree, typical current.

Note 2: LED circuit :



4. Interface Pin Assignment

4.1 LCM Pin Assignment

No.	Symbol	Description
1	VDD 2.8V	Power supply (2.8V)
2	TE 1.8V	Tearing effect signal is used to synchronize MCU to frame memory writing
3	GND	Ground
4	SDI 1.8V	Serial data input (1.8V)
5	DCX 1.8V	Display data/command selection pin in parallel interface(1.8V)
6	SCL1.8V	Serial clock signal (1.8V)
7	CSX 1.8V	Chip select input signal (1.8V)
8	RESX 1.8V	Global reset pin (1.8V)
9	VDDI 1.8V	Power supply (1.8V)
10	GND	Ground
11	LEDK	Power for LED backlight (Cathode)
12	LEDA	Power for LED backlight (Anode)

5. Interface Characteristics

5.1 Power Sequence

VDDI and VDD can be applied in any order.

In CABC function application, VDDI power on need delay 5ms after VDD has been supplied. VDD and VDDI can be power down in any order.

During power off, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down minimum 120msec after RESX has been released.

During power off, if LCD is in the Sleep In mode, VDDI or VDD can be powered down minimum 0msec after RESX has been released.

CSX can be applied at any timing or can be permanently grounded. RESX has priority over CSX.

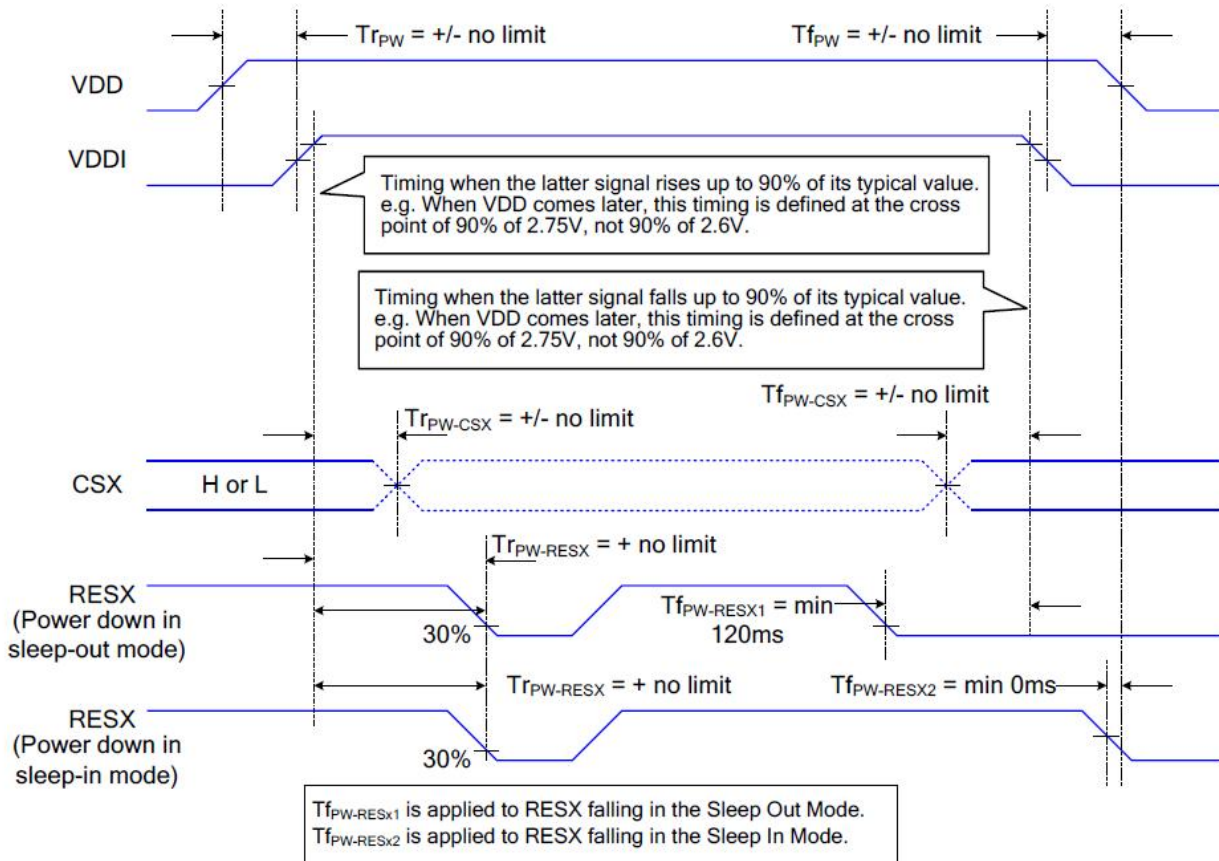
Note 1: There will be no damage to the display module if the power sequences are not met.

Note 2: There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.

Note 3: There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out command. Also between receiving Sleep In command and Power Off Sequence.

Note 4: If RESX line is not held stable by host during Power On Sequence as defined in the sequence below, then it will be necessary to apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is not guaranteed.

The power on/off sequence is illustrated below:



5.2 DC Characteristics

Parameter	Symbol	Condition	Specification			Unit	Related Pins
			MIN.	TYP.	MAX.		
Power & Operation Voltage							
System Voltage	VDD	Operating voltage	2.4	2.75	3.3	V	
Interface Operation Voltage	VDDI	I/O Supply Voltage	1.65	1.8	3.3	V	
Gate Driver High Voltage	VGH		12.2		14.97	V	Note 4
Gate Driver Low Voltage	VGL		-12.5		-7.16	V	
Gate Driver Supply Voltage		VGH-VGL	19.36		27.47	V	Note 5
Input / Output							
Logic-High Input Voltage	VIH		0.7VDDI		VDDI	V	Note 1
Logic-Low Input Voltage	VIL		VSS		0.3VDDI	V	Note 1
Logic-High Output Voltage	VOH	IOH = -1.0mA	0.8VDDI		VDDI	V	Note 1
Logic-Low Output Voltage	VOL	IOL = +1.0mA	VSS		0.2VDDI	V	Note 1
Logic-High Input Current	IIH	VIN = VDDI			1	uA	Note 1
Logic-Low Input Current	IIL	VIN = VSS	-1			uA	Note 1
Input Leakage Current	IIL	IOH = -1.0mA	-0.1		+0.1	uA	Note 1
VCOM Voltage							
VCOM amplitude	VCOM			VSS		V	
Source Driver							
Source Output Range	Vsout		VAN		VAP	V	
Gamma Reference Voltage(Positive)	VAP		4.45		6.4	V	Note 6
Gamma Reference Voltage(Negative)	VAN		-4.6		-2.65	V	
Source Output Settling Time	Tr	Below with 99% precision			20	us	Note 2
Output Offset Voltage	VOFFSET				35	mV	Note 3

Table 2 Basic DC Characteristics

5.3 AC Characteristics

5.2.1 Serial Interface Characteristics (4-line serial):

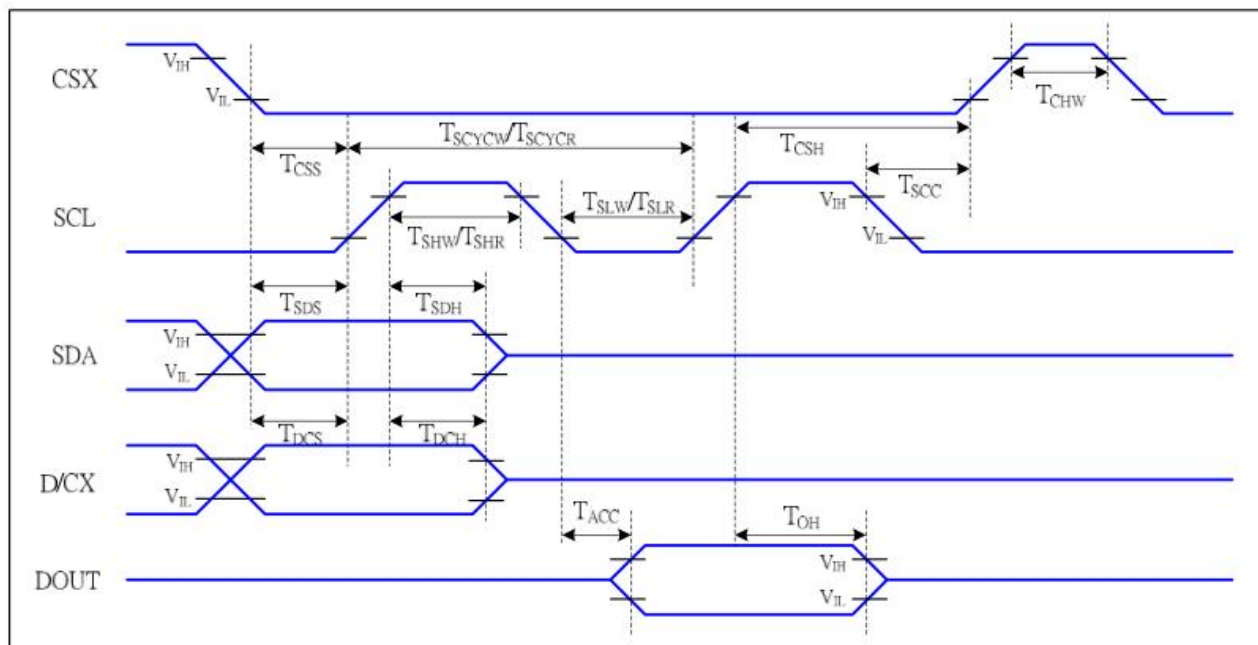


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYCW}	Serial clock cycle (Write)	16		ns	-write command & data ram
	T _{SHW}	SCL "H" pulse width (Write)	7		ns	
	T _{SLW}	SCL "L" pulse width (Write)	7		ns	
	T _{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T _{DCS}	D/CX setup time	10		ns	
	T _{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T _{SDS}	Data setup time	7		ns	
	T _{SDH}	Data hold time	7		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T _{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

5.4 Reset Timing

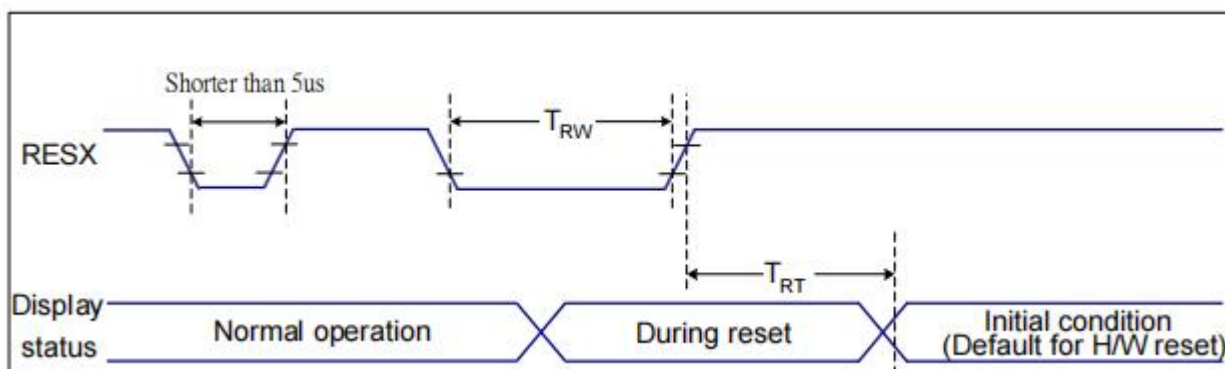


Figure 7 Reset Timing

$VDD_1=1.65$ to $3.3V$, $VDD_2=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a=25^{\circ}C$

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
			-	120 (Note 1, 6, 7)	ms

Table 8 Reset Timing

5.5 Table for the setting limitation of RGB interface signals

Parameter	Symbol	Min.	Typ.	Max.	Unit
Horizontal Sync. Width	hpw	6	30	hpw+hbp=93	Clock
Horizontal Sync. Back Porch	hbp	12	30		Clock
Horizontal Sync. Front Porch	hfp	6	60	-	Clock
Vertical Sync. Width	vs	2	4	vs+vbp=127	Line
Vertical Sync. Back Porch	vbp	2	4		Line
Vertical Sync. Front Porch	vfp	2	8	-	Line

Note:

Typical value are related to the setting of dot clock is 17MHz and frame rate is 60Hz.

In with ram mode, $hpw+hbp+hfp \geq 66$

In without ram mode, $hpw+hbp \geq 60$

6. Optical Specifications

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR≥10) B/L ON	θ_T	$\Phi=90^\circ$ (12 o'clock)	80	85	-	deg	Note2
	θ_B	$\Phi=270^\circ$ (6 o'clock)	80	85	-	deg	Note2
	θ_L	$\Phi=180^\circ$ (9 o'clock)	80	85	-	deg	Note2
	θ_R	$\Phi=0^\circ$ (3 o'clock)	80	85	-	deg	Note2
Response Time	T_{ON}	Normal $\theta=\Phi=0^\circ$	-	15	17	msec	Note4
	T_{OFF}		-	15	17	msec	Note4
Contrast Ratio	CR		800	1000	-	-	Note1 Note3
Color Chromaticity	W_X		0.2655	0.2955	0.3255	-	Note1 Note5
	W_Y		0.2782	0.3082	0.3382	-	Note1 Note5
Luminance	L		480	580	-	cd/m ²	Note1 Note7
Luminance Uniformity	Y_U		75	80	-	%	Note1 Note6
NTSC	-		55	60	-	%	-

Note 1: Definition of optical measurement system

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.

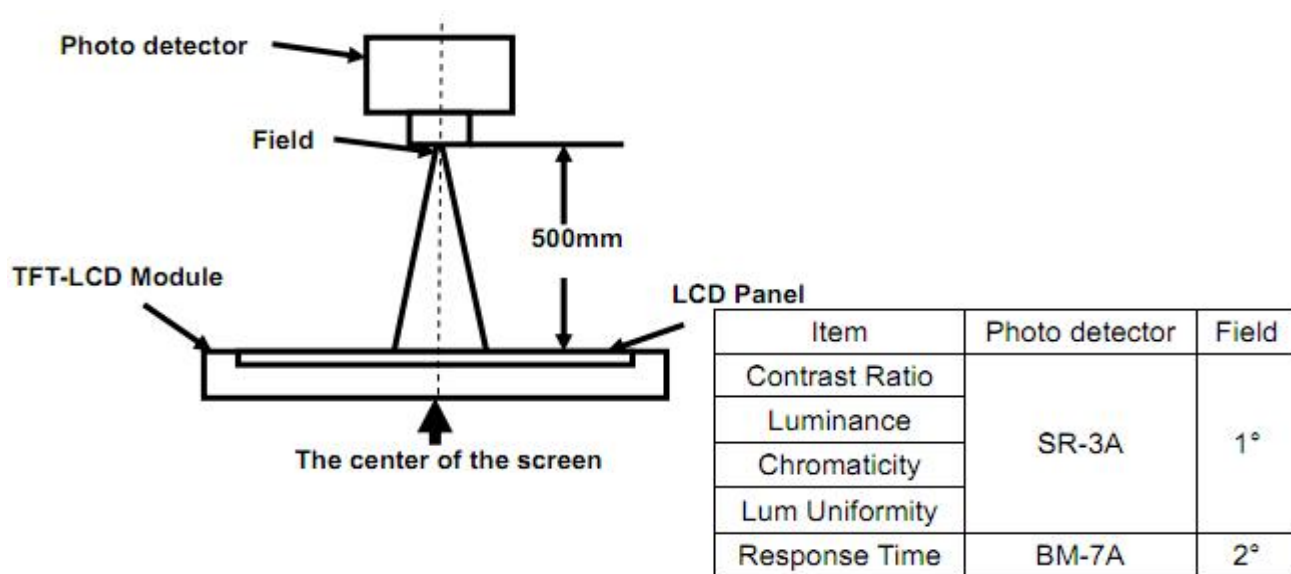


Fig 1

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).

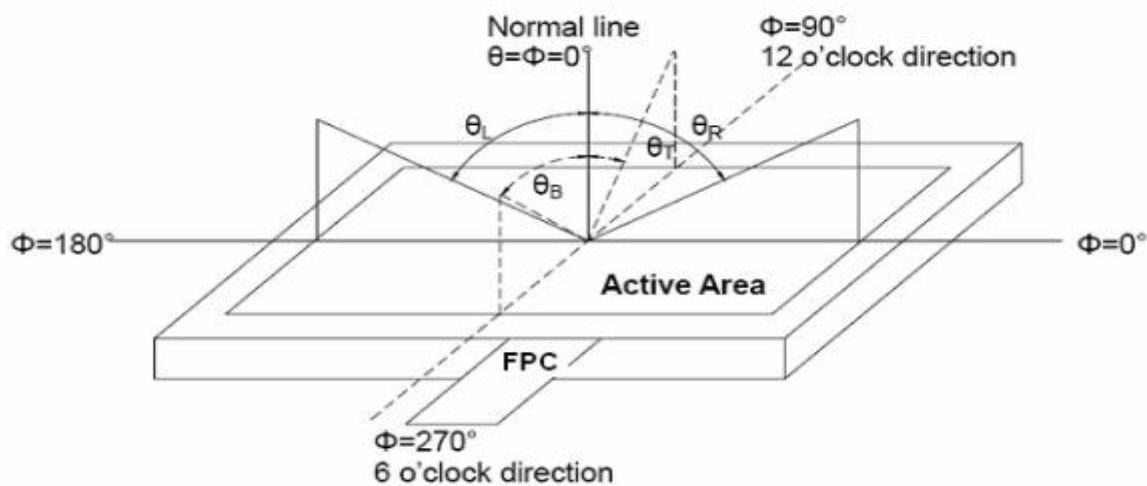


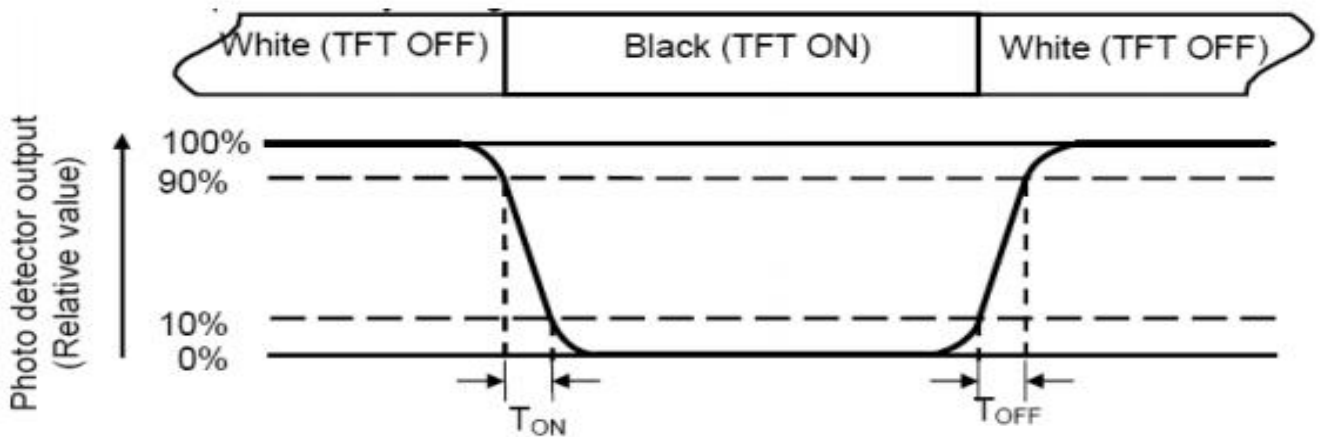
Fig 2 Definition of viewing angle

Note 3: Definition of contrast ratio

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.3-a/b

Note 7: Surface luminance is the luminance with all pixels displaying white.

L_v = Average Surface Luminance with all white pixels ($P_1, P_2, P_3, \dots, P_n$)

For more information see FIG.3-a/b

Note 8:

H,V : Active area(see Figure a)

Light spot size $\varnothing = 5\text{mm}$ (BM-5) or $\varnothing = 7.7\text{mm}$ (BM-7) 50cm distance or test spot position : see Figure a.

measurement instrument : TOPCON's luminance meter SR-3A or BM-7 or compatible (see Figure 1).

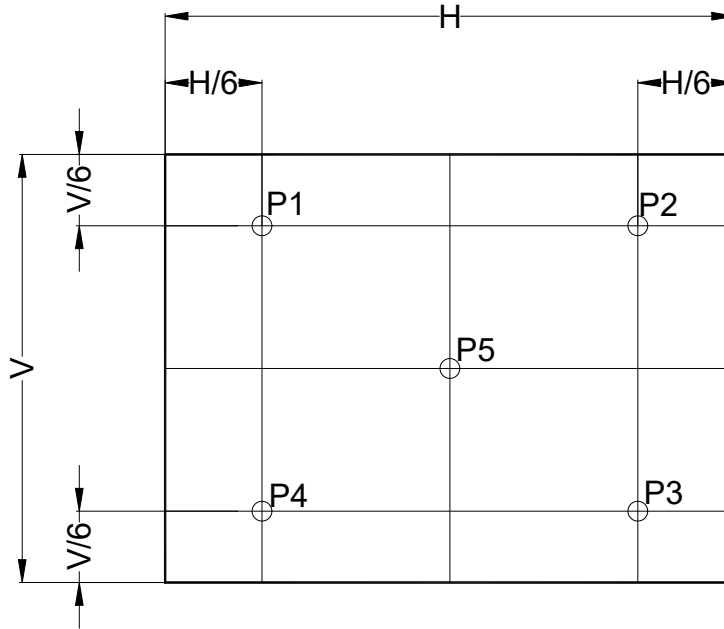


Fig. 3-a Definition of points

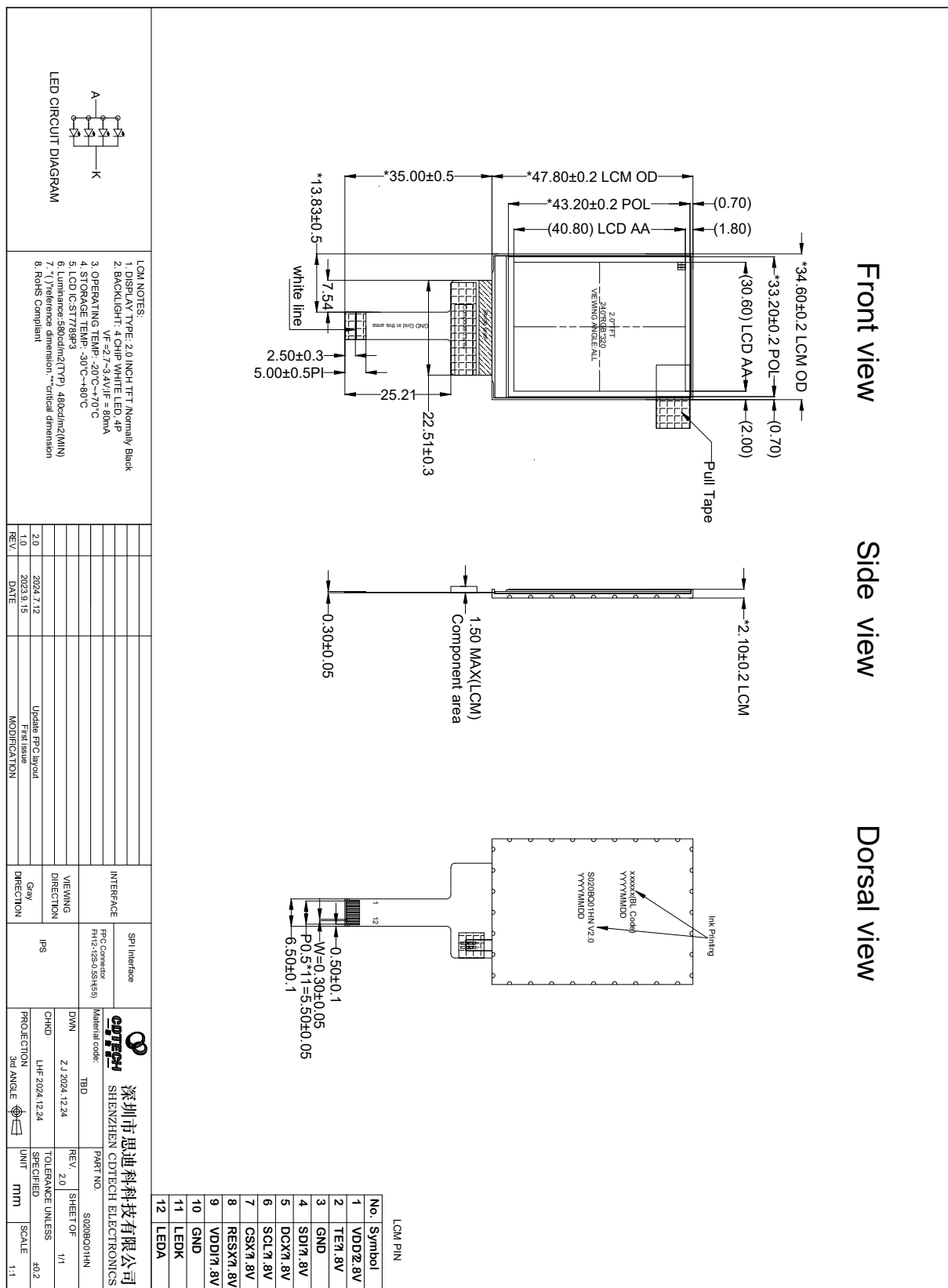
7. Reliability Test Items

Test Item	Test Conditions
High Temperature Storage	Ta= +80℃ 96hrs
Low Temperature Storage	Ta= -30℃ 96hrs
High Temperature Operation	Ta= +70℃ 96hrs
Low Temperature Operation	Ta= -20℃ 96hrs
High Temperature and Humidity Storage	Ta= +60℃, 90% RH 96hrs
Thermal Shock (Non-operation)	-30℃/30 min ~ +80℃/30 min for 20 cycles Start with cold temperature end with high temperature
Electro Static Discharge	Contact = ± 4 kV, class B Air = ± 8 kV, class B R=330Ω,C=150pF
Vibration	Sweep: 10Hz~55Hz~10Hz Stroke: 1.5mm 2 hrs for each direction of X .Y. Z.
Mechanical Shock	60G 6ms,±X,±Y,±Z 3 times for each direction
Package Drop Test	Height: 60 cm 1 corner, 3 edges, 6 surfaces

Notes: The test result shall be evaluated after the sample has been left at room temperature and humidity for 2 hours without load. No condensation shall be accepted. The sample will not be accepted if appear these defects:

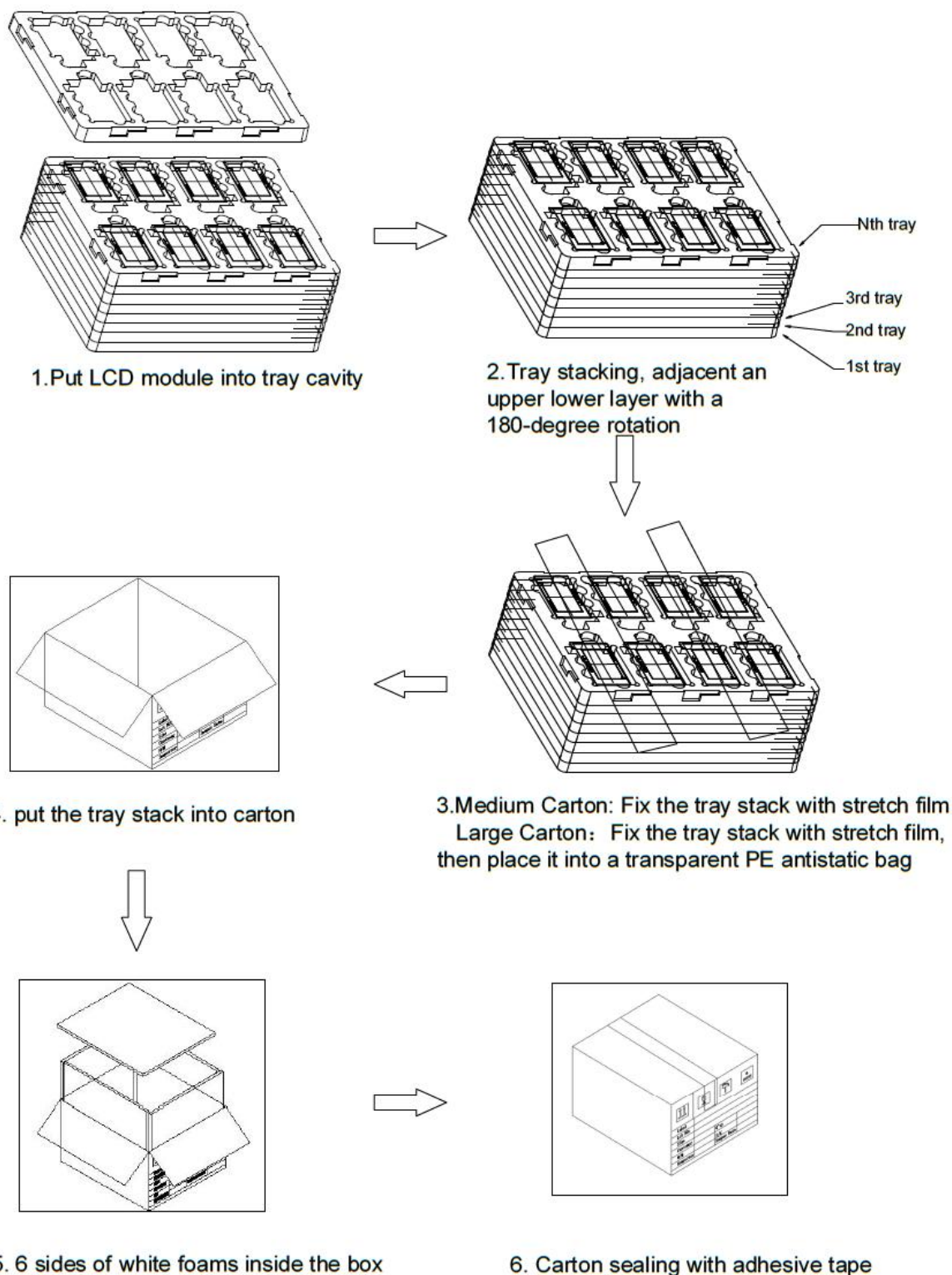
- 1). Air bubble in the LCD
- 2). Seal leak or Glass crack
- 3). Non display or abnormal display
- 4). Brightness reduction >50%

8. Mechanical Drawing



9. Packing

Packing Method



10. Precautions for Use of LCD modules

10.1 Handling Precautions

10.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

10.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

10.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

10.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

10.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

- Isopropyl alcohol
- Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents

10.1.6. Do not attempt to disassemble the LCD Module.

10.1.7. If the logic circuit power is off, do not apply the input signals.

10.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

10.1.8.1. Be sure to ground the body when handling the LCD Modules.

10.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.

10.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

10.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

10.2 Storage Precautions

10.2.1. When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

10.2.2. The LCD modules should be stored under the storage temperature range if the LCD modules will be stored for a long time, the recommend condition is :

Temperature : 0℃ ~40℃ Relatively humidity: ≤80%

10.2.3. The LCD modules should be stored in the room without acid, alkali and harmful gas.

10.3 Transportation Precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

10.4 Packaging instructions

When the customers using trays, they have to stack the adjacent trays in a 180° staggered to prevent pressure that could cause product damage.